

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



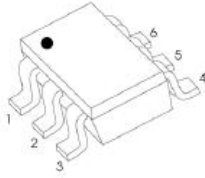
GDT



PLED

Product data sheet

[www.msksemi.com](http://www.msksemi.com)

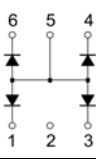
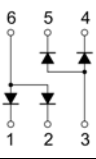
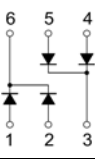
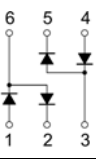








SOT-363

## Switching Diode

### FEATURES

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance Power Dissipation

MMBD4448HAEW	MMBD4448HADW	MMBD4448HCDW	MMBD4448HSDW	MMBD4448HTW
				
MARKING:KA5	MARKING:KA6	MARKING:KA7	MARKING:KAB	MARKING:KAA
				

Solid dot = Pin1 indicate.

Solid dot = Green molding compound device, if none, the normal device.

### Maximum Ratings and Electrical Characteristics, Single Diode @T<sub>a</sub>=25 °C

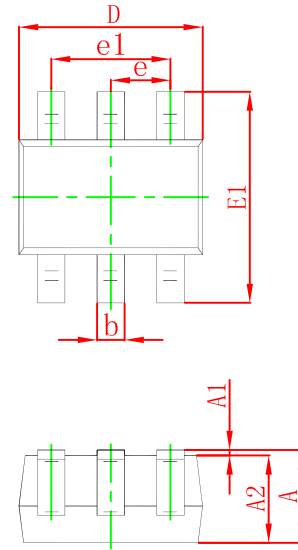
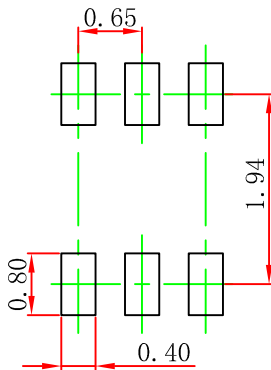
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	80	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	57	V
Forward Continuous Current	I <sub>FM</sub>	500	mA
Average Rectified Output Current	I <sub>O</sub>	250	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I <sub>FSM</sub>	2.0	A
Power Dissipation	P <sub>d</sub>	200	mW
Thermal Resistance from Junction to Ambient	R <sub>θJA</sub>	625	°C/W
Storage Temperature	T <sub>STG</sub>	-55 ~+150	°C

## ELECTRICAL CHARACTERISTICS

### Electrical Ratings @Ta=25°C

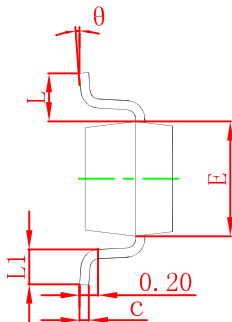
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse Breakdown Voltage	$V_{(BR)}$	80			V	$I_R=100\mu A$
Forward Voltage	$V_{F1}$	0.62		0.72	V	$I_F=5mA$
	$V_{F2}$			0.855	V	$I_F=10mA$
	$V_{F3}$			1.0	V	$I_F=100mA$
	$V_{F4}$			1.25	V	$I_F=150mA$
Reverse Current	$I_{R1}$			100	nA	$V_R=70V$
	$I_{R2}$			25	nA	$V_R=20V$
Capacitance Between Terminals	$C_T$			3.5	pF	$V_R=0V, f=1MHz$
Reverse Recovery Time	$t_{rr}$			4	ns	$I_F=I_R=10mA$ $I_{rr}=0.1I_R, R_L=100\Omega$

SOT-363



Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°

**REEL SPECIFICATION**

P/N	PKG	QTY
MMBD4448	SOT-363	3000

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